

**MOLD COMPOUND CAP IN A
FLIP CHIP MULTI-MATRIX ARRAY PACKAGE
AND PROCESS OF MAKING SAME**

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ABSTRACT OF THE DISCLOSURE

10 A molding compound cap structure is disclosed. A process of forming the
molding compound cap structure is also disclosed. A microelectronic package is
also disclosed that uses the molding compound cap structure. A method of
assembling a microelectronic package is also disclosed. A computing system is also
disclosed that includes the molding compound cap structure. The molding
compound cap includes a configuration that exposes a portion of a microelectronic
device.

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